



STB75NF75 STP75NF75 STP75NF75FP

N-CHANNEL 75V - 0.0095 Ω - 80A TO-220/TO-220FP/D2PAK STripFET™ II POWER MOSFET

TYPE	V _{DSS}	R _{DS(on)}	I _D
STB75NF75	75 V	<0.011 Ω	80 A
STP75NF75	75 V	<0.011 Ω	80 A
STP75NF75FP	75 V	<0.011 Ω	80 A(*)

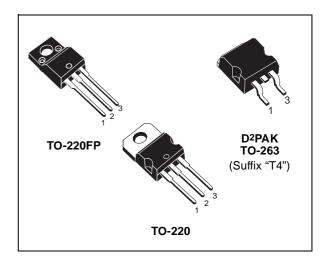
- TYPICAL $R_{DS}(on) = 0.0095 \Omega$
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- SURFACE-MOUNTING D²PAK (TO-263) POWER PACKAGE IN TAPE & REEL (SUFFIX "T4")

DESCRIPTION

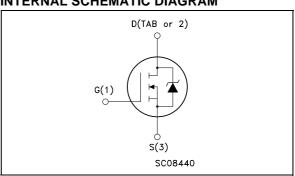
This MOSFET series realized with STMicroelectronics unique STripFET™ process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced highefficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any applications with low gate drive requirements.

APPLICATIONS

- SOLENOID AND RELAY DRIVERS
- DC MOTOR CONTROL
- DC-DC CONVERTERS
- AUTOMOTIVE ENVIRONMENT



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Va	alue	Unit
		STB75NF75 STP75NF75	STP75NF75FP	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	-	75	V
V_{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)		75	V
V _{GS}	Gate- source Voltage	±	20	V
I _D	Drain Current (continuous) at T _C = 25°C	80	80(*)	Α
I _D	Drain Current (continuous) at T _C = 100°C	70	70(*)	Α
I _{DM} (•)	Drain Current (pulsed)	320	320(*)	Α
P _{tot}	Total Dissipation at T _C = 25°C	300	45	W
	Derating Factor	2.0	0.3	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope		12	V/ns
E _{AS} (2)	Single Pulse Avalanche Energy	7	'00	mJ
V _{ISO}	Insulation Withstand Voltage (DC)		2000	V
T _{stg}	Storage Temperature	55	to 175	°C
Tį	Operating Junction Temperature	-33	10 173	

Pulse width limited by safe operating area.
 Refer to SOA for the max allowable current values on FP-type

due to Rth value

⁽¹⁾ $I_{SD} \le 80A$, $di/dt \le 300A/\mu s$, $V_{DD} \le V_{(BR)DSS}$, $T_i \le T_{JMAX}$

⁽²⁾ Starting $T_i = 25 \text{ °C}$, $I_D = 40 \text{A}$, $V_{DD} = 37.5 \text{V}$



THERMAL DATA

			D ² PAK TO-220	TO-220FP	
Rthj-case	Thermal Resistance Junction-case	Max	0.5	3.33	°C/W
Rthj-amb T _l	Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose (1.6 mm from case, for 10 sec.)	Max	62 30	-	°C/W °C

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	75			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating T_C = 125^{\circ}C$			1 10	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			±100	nA

ON (*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu A$	2	3	4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V	I _D = 40 A		0.0095	0.011	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} = 15 V I _D = 40 A		20		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$, $f = 1 MHz$, $V_{GS} = 0$		3700 730 240		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on Delay Time Rise Time	$\begin{aligned} &V_{DD} = 37.5 \text{ V} & I_{D} = 45 \text{ A} \\ &R_{G} = 4.7 \Omega & V_{GS} = 10 \text{ V} \\ &\text{(Resistive Load, Figure 3)} \end{aligned}$		25 25		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V _{DD} = 60 V I _D = 80 A V _{GS} = 10V		117 27 47	160	nC nC nC

SWITCHING OFF

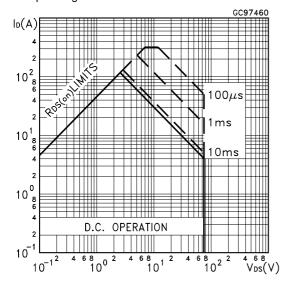
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time	$\begin{aligned} &V_{DD} = 37.5 \text{ V} & I_{D} = 45 \text{ A} \\ &R_{G} = 4.7 \Omega & V_{GS} = 10 \text{ V} \\ &(\text{Resistive Load, Figure 3}) \end{aligned}$		66 30		ns ns

SOURCE DRAIN DIODE

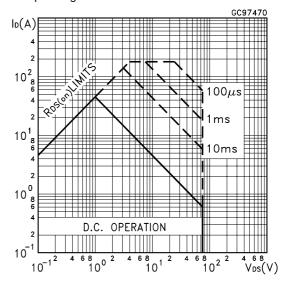
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (•)	Source-drain Current Source-drain Current (pulsed)				80 320	A A
V _{SD} (*)	Forward On Voltage	I _{SD} = 80 A V _{GS} = 0			1.5	V
t _{rr} Q _{rr} IRRM	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$\begin{split} I_{SD} = 80 \text{ A} & \text{di/dt} = 100 \text{A/}\mu\text{s} \\ V_{DD} = 25 \text{ V} & T_j = 150 ^{\circ}\text{C} \\ \text{(see test circuit, Figure 5)} \end{split}$		132 660 10		ns nC A

^(*)Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

Safe Operating Area

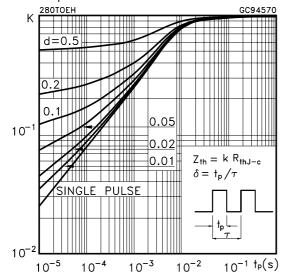


Safe Operating Area for TO-220FP

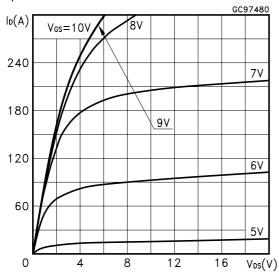




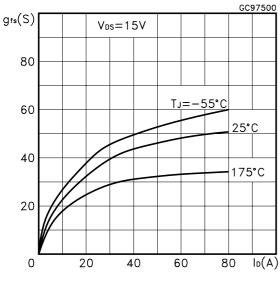




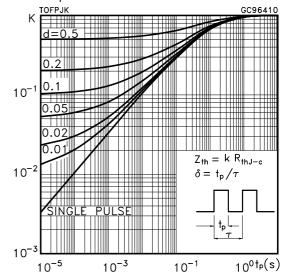
Output Characteristics



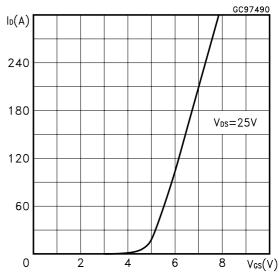
Transconductance



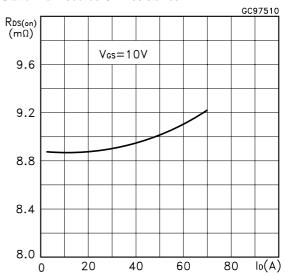
Thermal Impedance for TO-220FP



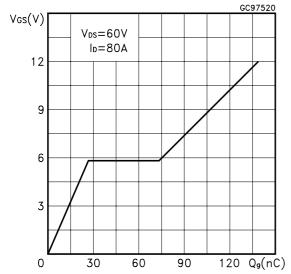
Transfer Characteristics



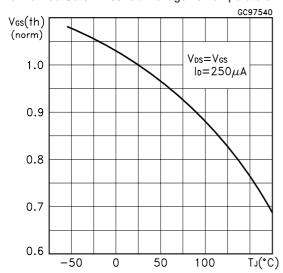
Static Drain-source On Resistance



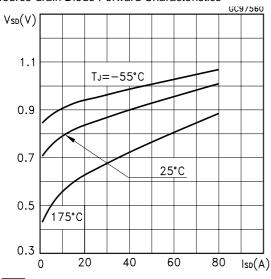
Gate Charge vs Gate-source Voltage



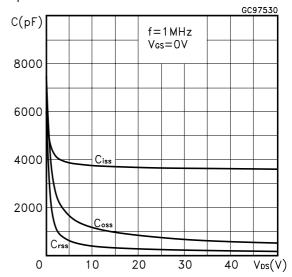
Normalized Gate Threshold Voltage vs Temperature



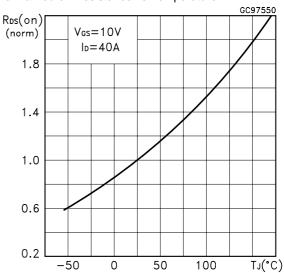
Source-drain Diode Forward Characteristics



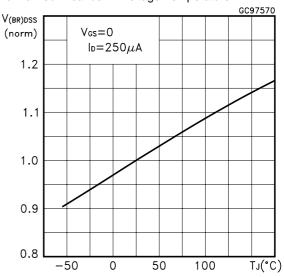
Capacitance Variations



Normalized on Resistance vs Temperature



Normalized Breakdown Voltage Temperature



5



Fig. 1: Unclamped Inductive Load Test Circuit

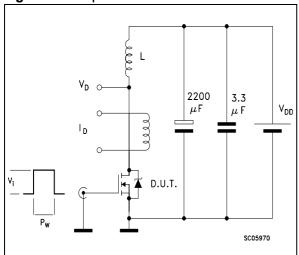


Fig. 3: Switching Times Test Circuits For Resistive Load

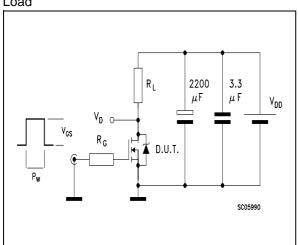


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

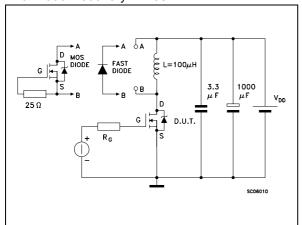


Fig. 2: Unclamped Inductive Waveform

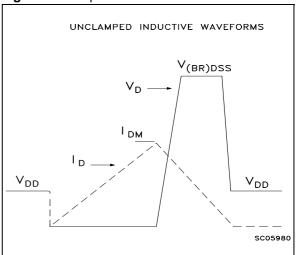
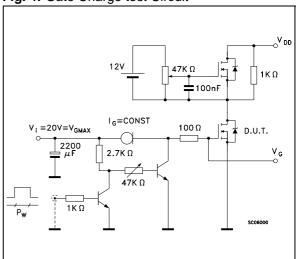


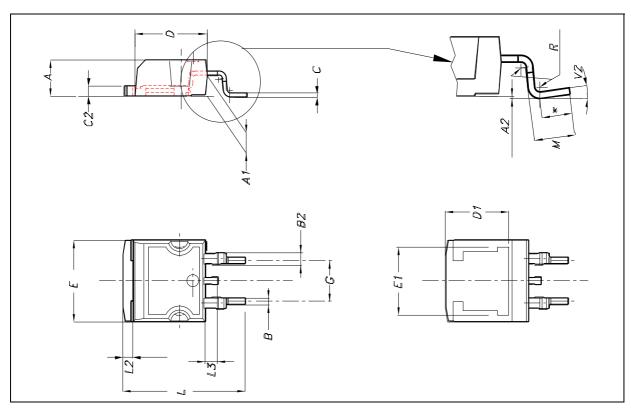
Fig. 4: Gate Charge test Circuit





D²PAK MECHANICAL DATA

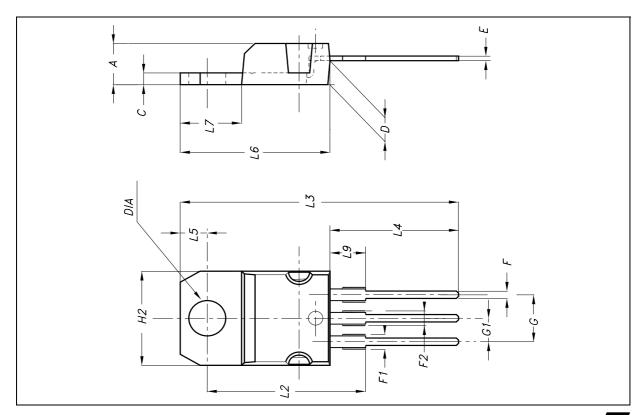
DIM.		mm.			inch.	
DINI.	MIN.	TYP.	MAX.	MIN.	TYP.	TYP.
Α	4.4		4.6	0.173		0.181
A 1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
В	0.7		0.93	0.028		0.037
B2	1.14		1.7	0.045		0.067
С	0.45		0.6	0.018		0.024
C2	1.21		1.36	0.048		0.054
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.394		0.409
E1	8.5				0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.591		0.624
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.069
М	2.4		3.2	0.094		0.126
R		0.4			0.016	
V2	0°		8°	0°		8°





TO-220 MECHANICAL DATA

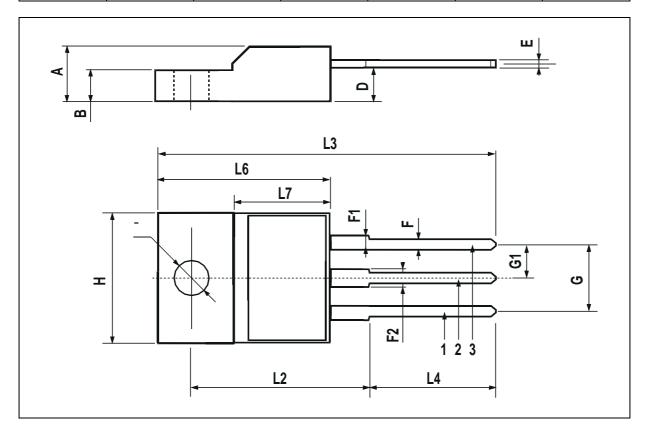
DIM.		mm.			inch.	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	TYP.
Α	4.4		4.6	0.173		0.181
С	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
Е	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.40		2.70	0.094		0.106
H2	10		10.40	0.393		0.409
L2		16.40			0.645	
L3		28.90			1.137	
L4	13		14	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.20		6.60	0.244		0.260
L9	3.50		3.93	0.137		0.154
DIA	3.75		3.85	0.147		0.151





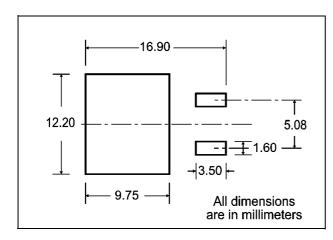
TO-220FP MECHANICAL DATA

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
Е	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126

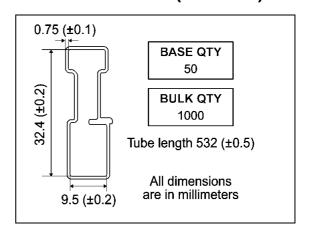




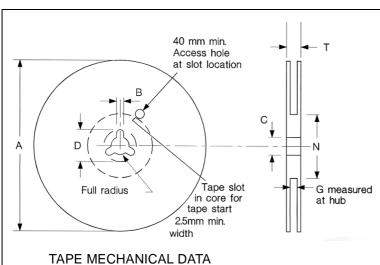
D2PAK FOOTPRINT



TUBE SHIPMENT (no suffix)*



TAPE AND REEL SHIPMENT (suffix "T4")*

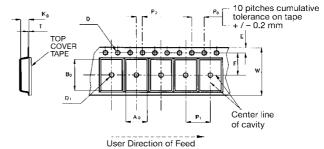


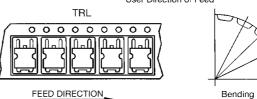
REEL MECHANICAL DATA

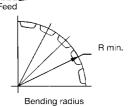
DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
Α		330		12.992
В	1.5		0.059	
С	12.8	13.2	0.504	0.520
D	20.2		0.795	
G	24.4	26.4	0.960	1.039
N	100		3.937	
T		30.4		1.197

BASE QTY	BULK QTY	
1000	1000	

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	10.5	10.7	0.413	0.421
В0	15.7	15.9	0.618	0.626
D	1.5	1.6	0.059	0.063
D1	1.59	1.61	0.062	0.063
Е	1.65	1.85	0.065	0.073
F	11.4	11.6	0.449	0.456
K0	4.8	5.0	0.189	0.197
P0	3.9	4.1	0.153	0.161
P1	11.9	12.1	0.468	0.476
P2	1.9	2.1	0075	0.082
R	50		1.574	
Т	0.25	0.35	.0.0098	0.0137
W	23.7	24.3	0.933	0.956







^{*} on sales type

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